
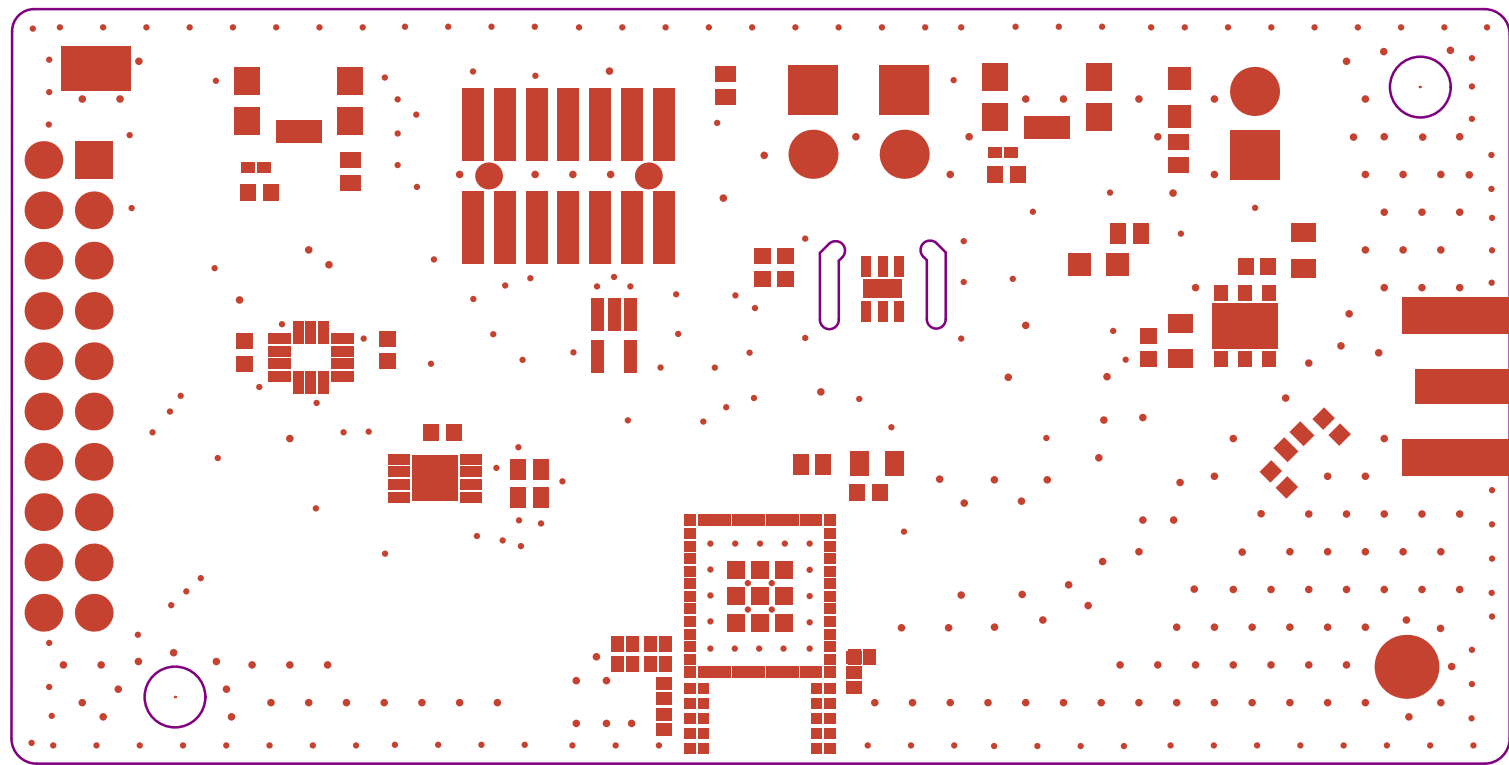

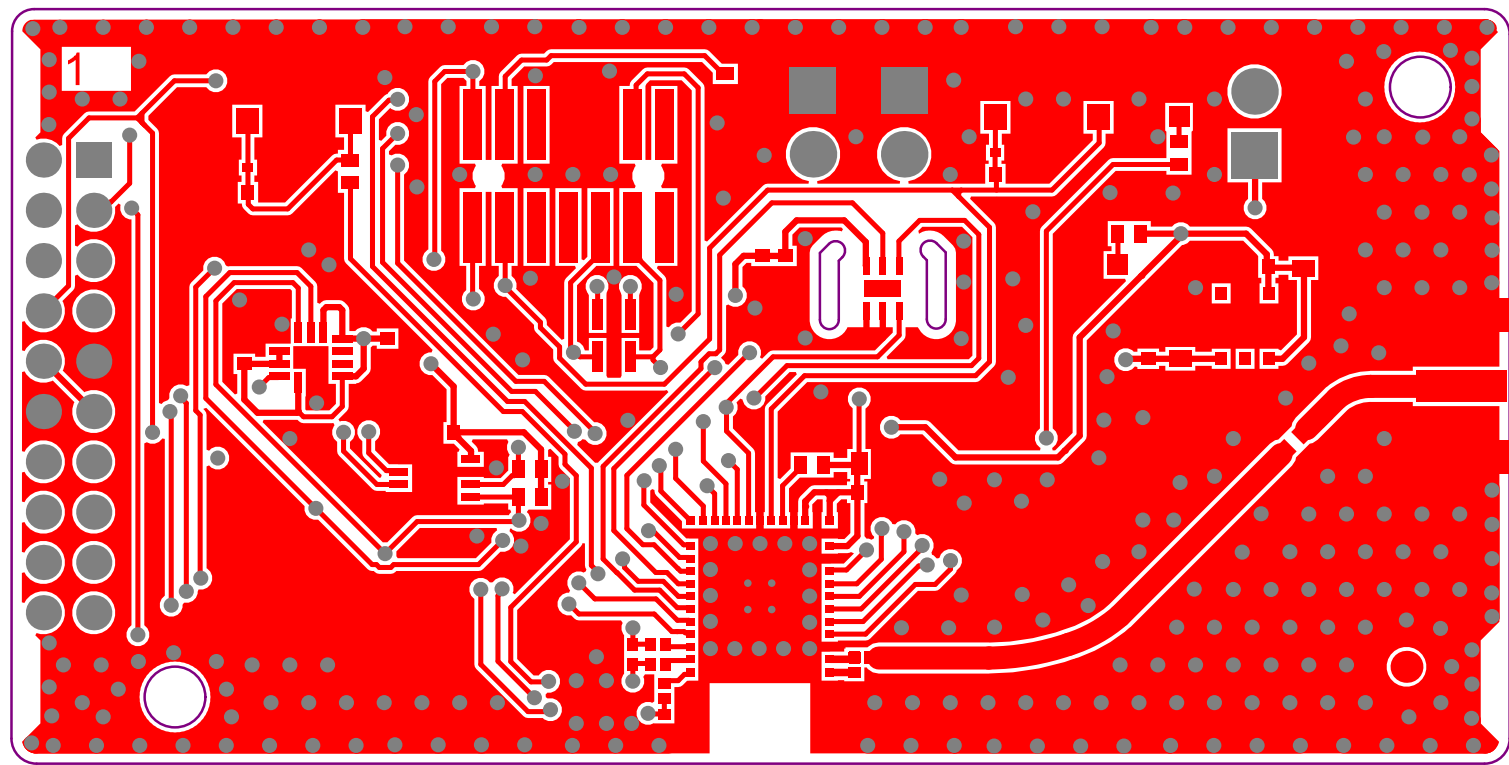



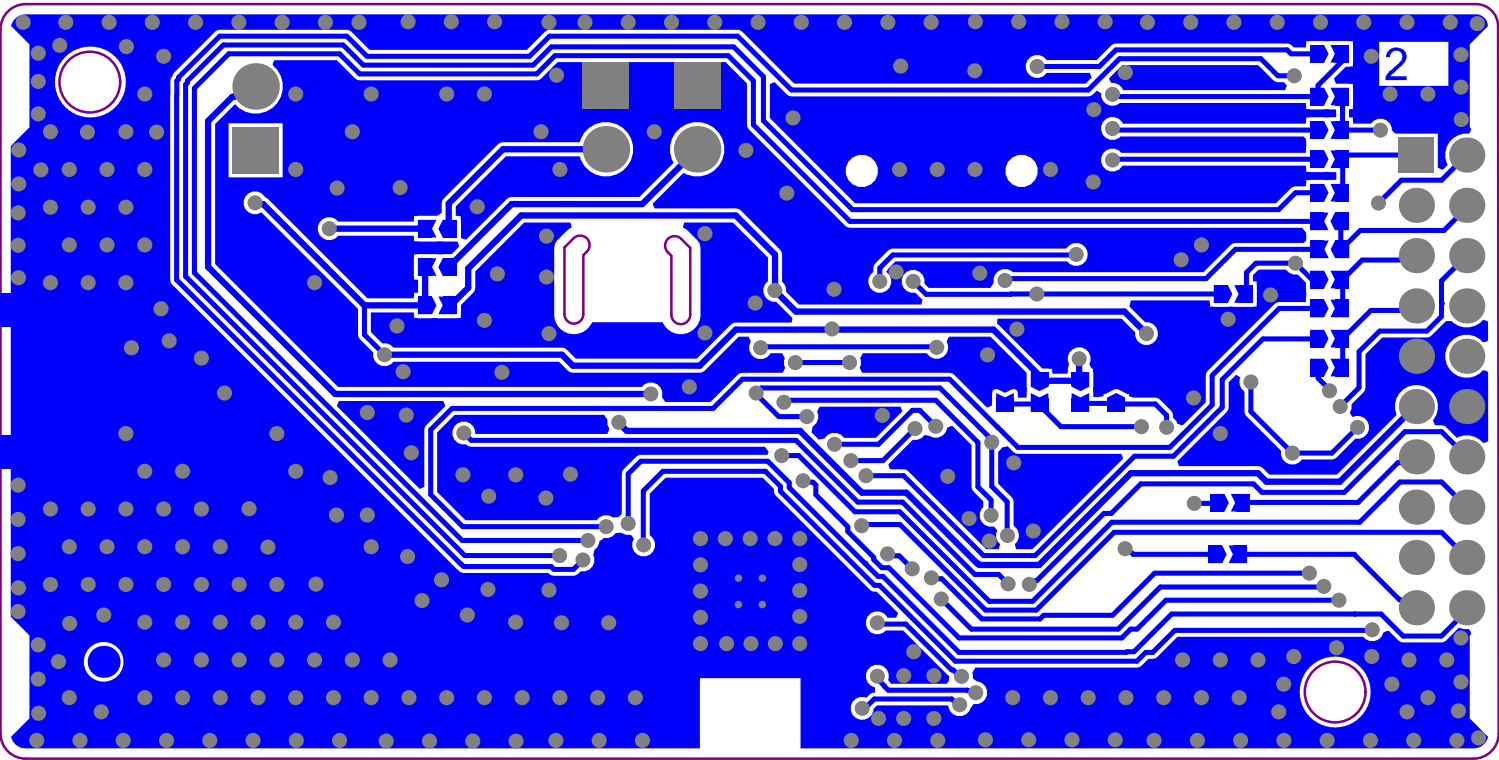
Project: STM32WB1M STMod+ expansion board		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB1868	
Date: 14-MAR-2023	Rev: D	




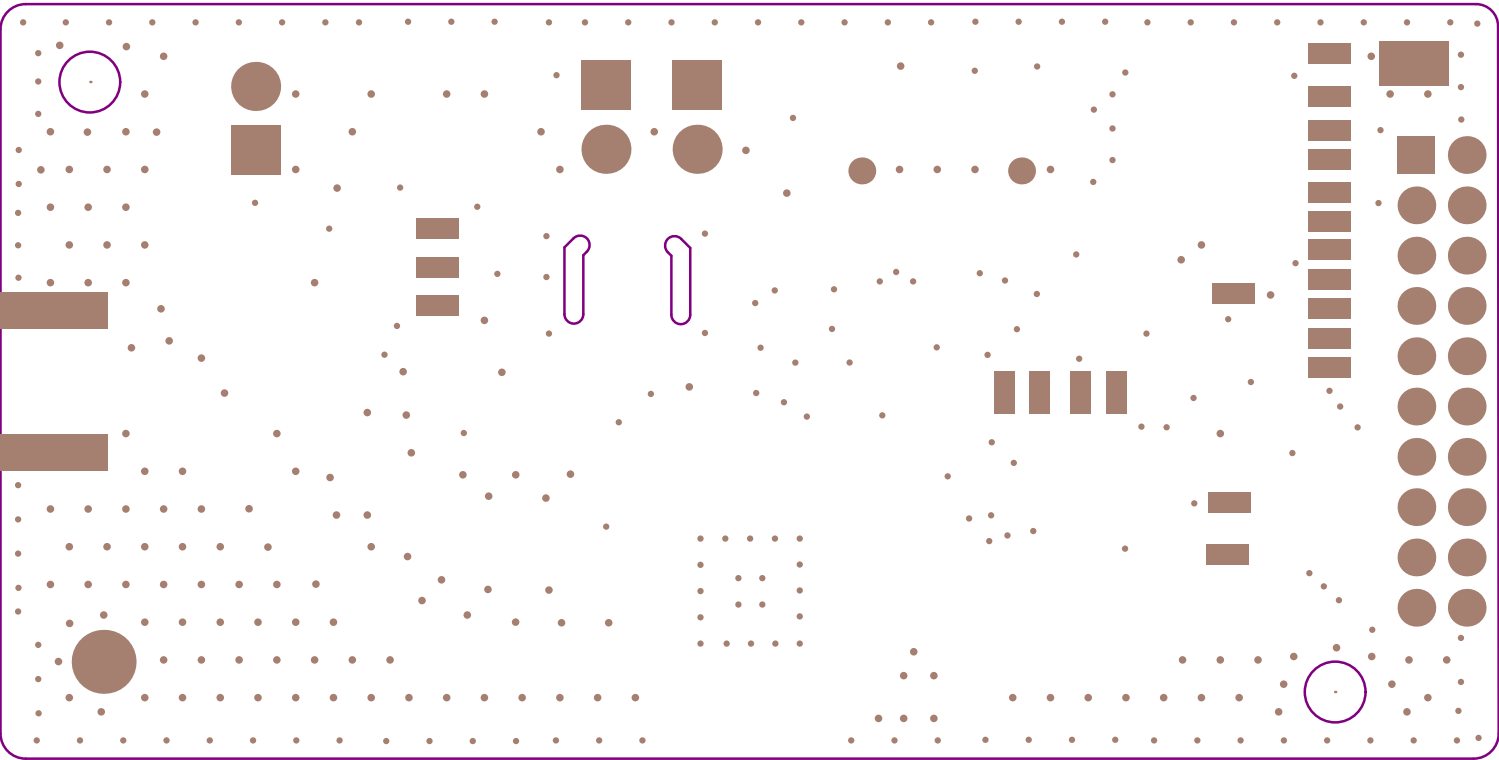
Project: STM32WB1M STMod+ expansion board		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1868	
Date: 14-MAR-2023	Rev: D	




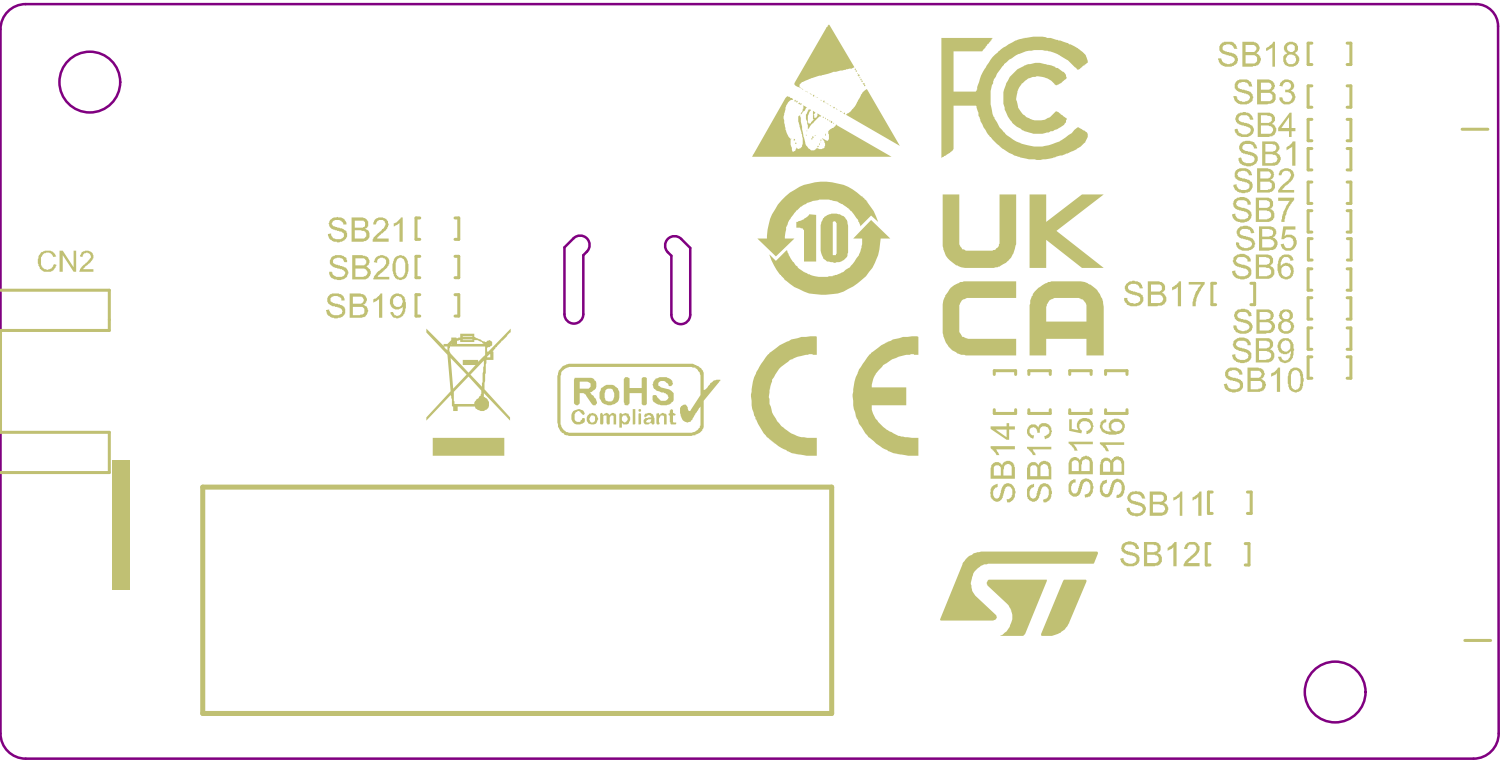
Project: STM32WB1M STMod+ expansion board		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1868	
Date: 14-MAR-2023	Rev: D	




Project: STM32WB1M STMod+ expansion board		
Layer: Bottom Layer	Gerber: .GBL	
Variant: [No Variations]	Ref: MB1868	
Date: 14-MAR-2023	Rev: D	



Project: STM32WB1M STMod+ expansion board		
Layer: Bottom Solder	Gerber: .GBS	
Variant: [No Variations]	Ref: MB1868	
Date: 14-MAR-2023	Rev: D	



Project: STM32WB1M STMod+ expansion board		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	Ref: MB1868	
Date: 14-MAR-2023	Rev: D	

MINIMUM PARAMETERS	PCB : TYPE 2
DEFAULT TRACKS : 0.20mm GAPS : 0.15mm	ASPECT-RATIO, AXE Z : < 6:1 LEVEL "A"

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐TG-170

☐TG-150

☒TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐GREEN

☐WHITE

☐RED

☒Blue ink PANTONE 2955

D. SILKSCREEN COLOR :

☒WHITE

☐YELLOW

☐BLACK

☐Blue ink PANTONE 2955

E. SURFACE FINISH :

☒ENIG

☐IMMERSION SILVER

☐IMMERSION TIN

☐HASL

☐HASL (PB-FREE)

☐GOLDEN FINGER

F. IMPEDANCE CONTROL :

☐NO

☐YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

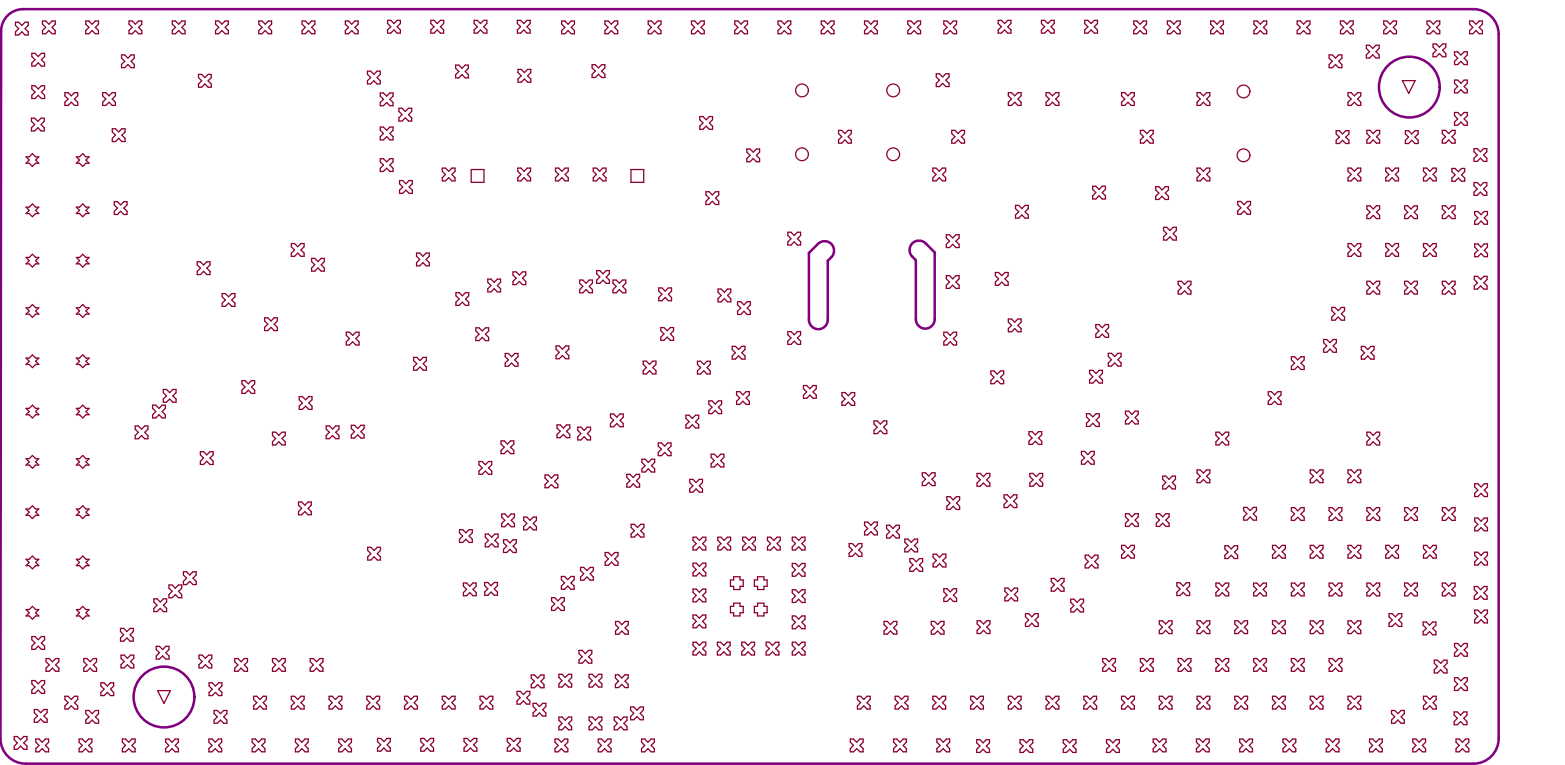
G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒SOLDERMASK


☐NON-CONDUCTIVE EPOXY.







H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.020mm	4.2	
1	Top Layer		0.018mm		
	Dielectric 2	8 x 7628	1.464mm	4.2	
2	Bottom Layer		0.018mm		
	Bottom Solder	Solder Resist	0.020mm	4.2	
	Bottom Overlay				

Project: STM32WB1M STMod+ expansion board		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB1868	
Date: 14-MAR-2023	Rev: D	

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
	2	0.970mm (38.19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	2	2.500mm (98.43mil)	NPTH	Slot	Top Layer - Bottom Layer	Pad	Rounded
	4	0.100mm (3.94mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	6	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	20	0.900mm (35.43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
	364	0.150mm (5.91mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	398 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout